

**100% Material Declaration Data Sheet:
FGG400****Average Weight: 1.94g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (Grams)	Component Percent of Total
Silicon Die					0.04944	2.55%
	Silicon	7440-21-3	100.00		0.04944	
Die Attach Material					0.00792	0.41%
	Polymetric Resin	Trade Secret	3.00		0.00023766	
	Diester Resin	Trade Secret	20.00		0.00158440	
	Acrylate Resin	Trade Secret	7.00		0.00055454	
	Silver	7440-22-4	70.00		0.00554540	
Mold Compound					0.00175	0.09%
	SiO2 Filler	60676-86-0	86.20	Filler	0.00150850	
	Epoxy Resin A	Trade Secret	3.00		0.00005250	
	Epoxy Resin B	Trade Secret	3.00		0.00005250	
	Phenol Resin A	Trade Secret	3.00		0.00005250	
	Phenol Resin B	Trade Secret	3.00		0.00005250	
	Metal Hydroxide	Trade Secret	1.50		0.00002625	
	Carbon Black	1333-86-4	0.30		0.00000525	
Substrate					1.53596	79.17%
	Copper	7440-50-8	46.27	Metal Layer	0.71068869	
	Nickel	7440-02-0	0.60	Metal Layer	0.00921576	
	Gold	7440-57-5	0.13	Metal Layer	0.00199675	
	Glass Fiber (GF)	N/A	23.00		0.35327080	
	Halogen Fire Retardant	N/A	3.20		0.04915072	
	BT (core)	N/A	16.80		0.25804128	
	Solder Mask (EP)	N/A	10.00		0.15359600	
Gold Wire					0.01078	0.56%
	Gold	7440-57-5	100.00		0.01078	
Solder Balls					0.33415	17.22%
	Tin	7440-31-5	95.50		0.31911325	
	Silver	7440-22-4	4.00		0.01336600	
	Copper	7440-50-8	0.50		0.00167075	

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/06/06	1.0	Initial Xilinx release.
06/01/06	1.1	100 percent material declaration.
08/16/06	1.2	Corrected glass fiber percentage of component.
09/21/06	1.3	Updated component descriptions.
01/08/07	1.3.1	Corrected gold wire CAS number entry.
12/12/08	1.3.2	Typographical edits.
04/01/09	1.4	Revised the CAS number/description for the silver component of solder balls.

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